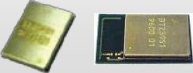


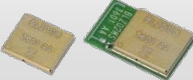
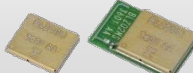



Wireless Module Lineup

	Bluetooth® Module			Bluetooth low energy Module		Wireless LAN Module
PN	MBH7BTZ39 MBH7BTZ40 MBH7BTZ42 MBH7BTZ43 	MBH7BTZ50 MBH7BTZ52 MBH7BTZ53 	MBH7BTZ39A MBH7BTZ42A 	MBH7BLZ01 MBH7BLZ02 	MBH7BLZ01-109003 MBH7BLZ02-109004 	MBH7WLZ30 
Type	Ver. 2.1+EDR, SPP embedded, Class 2	Ver. 2.1+EDR, SPP embedded, Class 2, for iOS accessory		Ver.4.0 (Single) Software embedded	Ver.4.0 (Single) 'Blank' module	802.11b/g
		CP chip on module	CP chip on customer PCB			
IC	CSR BC4-External			Nordic Semiconductor nRF51822		—
Attachment	BTZ39/42:SMD BTZ40/43: Connector	BTZ52:SMD BTZ50/BTZ53: Connector	SMD	SMD		SMD
Antenna	BTZ39: No BTZ40/42/43: Yes	Yes	BTZ39A: No BTZ42A: Yes	BLZ01: No BLZ02: Yes	109003: No 109004: Yes	No
Host I/F	UART					
Qualification /Certification	-QDID:B016058 -Japan: BTZ39/40/42/43 -FCC/IC/CE BTZ40/42/43	-QDID:B016058 -Japan: BTZ50/52/53 -FCC/IC/CE BTZ50/52/53	-QDID:B016058 -Japan: BTZ39A/42A -FCC/IC/CE BTZ42A	-QDID: B021902 -Japan: BLZ01 BLZ02 -FCC/IC/CE: BLZ02	-QDID: B021902 -Japan: BLZ01-109003 BLZ02-109004 -FCC/IC/CE: BLZ02-109004	Japan

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